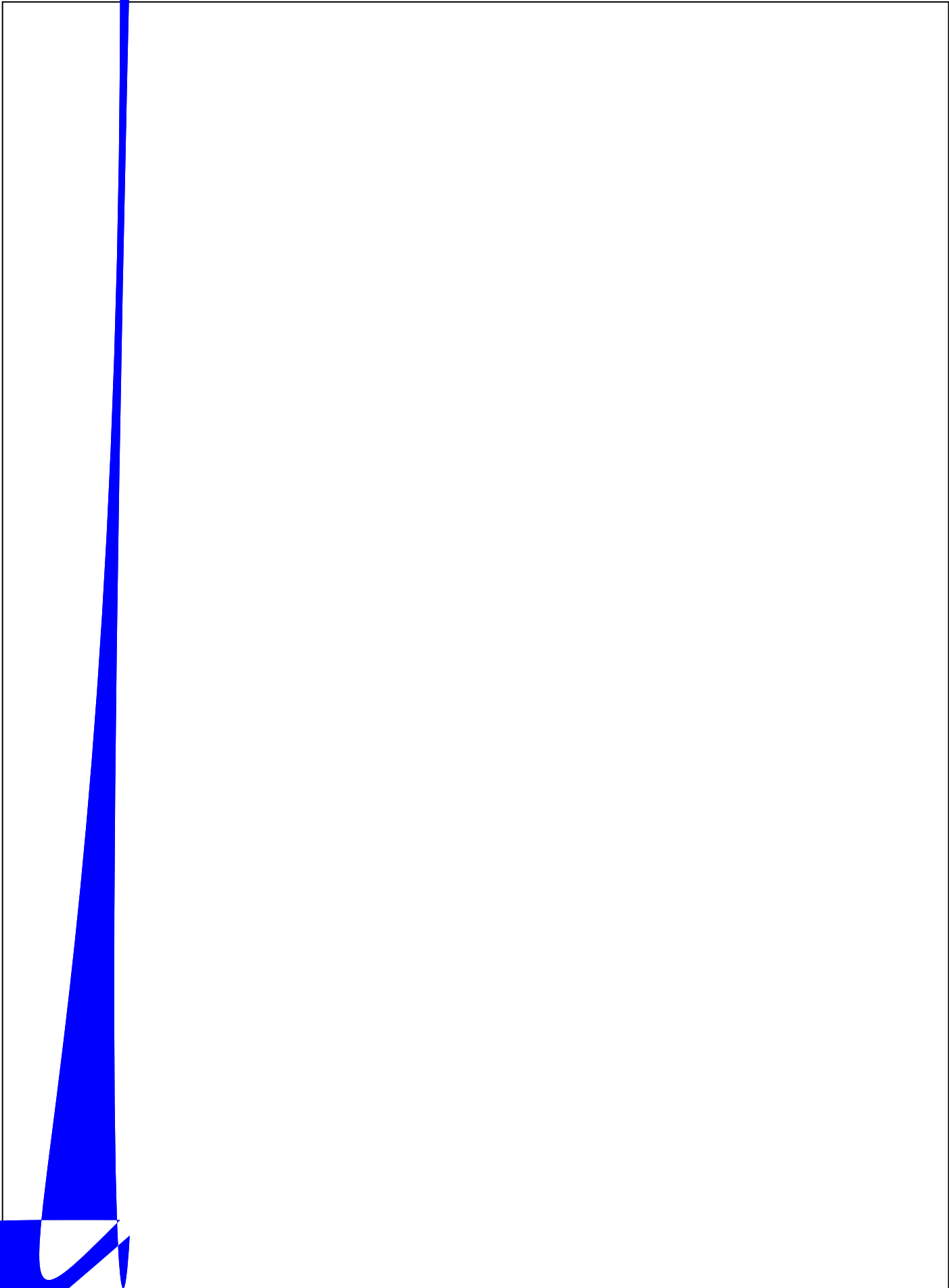
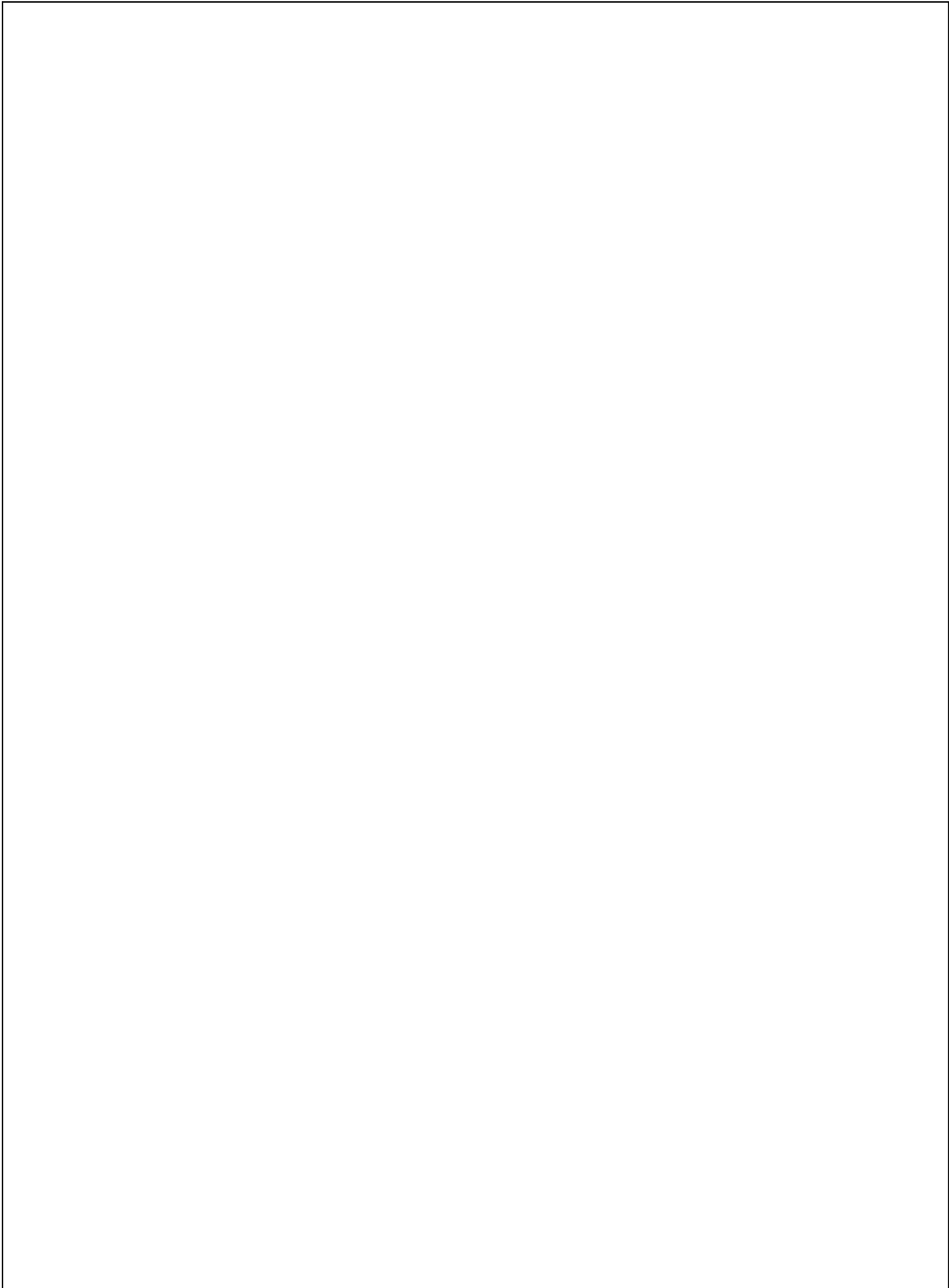


LIGHT





Electrical Optical Characteristics at Ta=25°C

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test Condition |
|---------------------------|----------------|------|------|------|-------|---------------------------------|
| Radiant Intensity | I _e | 2.2 | 3.0 | 4.4 | mW/sr | I _F =20mA (Note 1,3) |
| Viewing Angle | $\frac{1}{2}$ | --- | 130 | --- | Deg. | (Note 2) |
| Peak Wavelength | | --- | 940 | --- | nm | I _F =20mA |
| Spectral Line Half- Width | | --- | 50 | --- | nm | I _F =20mA |
| Forward Voltage | V _F | --- | 1.25 | 1.60 | V | I _F =50mA |
| Reverse Current | I _R | --- | --- | 100 | μA | V _R =5V |

Note:

1. Point sources of the amount of radiation per unit time in a given direction within the unit solid Angle radiated energy.
2. $\frac{1}{2}$ is the off-axis angle at which the Radiant Intensity is half the axial Radiant Intensity.
3. The I_e guarantee should be added ±15% tolerance.

Infrared Emitting Diode Specification

●Commodity: Infrared emitting diode

●Intensity Bin Limits (At 20mA)

| BIN CODE | Min. (mW/sr) | Max. (mW/sr) |
|----------|--------------|--------------|
| 18 | 2.2 | 2.6 |
| 19 | 2.6 | 3.1 |
| 20 | 3.1 | 3.7 |
| 21 | 3.7 | 4.4 |

NOTE: The I_e guarantee should be added ±15% tolerance.





LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures (Fig.1).

